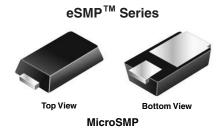


Vishay General Semiconductor

Surface Mount Schottky Barrier Rectifiers



PRIMARY CHARACTERISTICS				
I _{F(AV)}	1 A			
V_{RRM}	30 V, 40 V			
I _{FSM}	25 A			
V _F at I _F = 1.0 A	0.41 V			
T _J max.	150 °C			

TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, dc-to-dc converters, and protection applications.

FEATURES





- Ideal for automated placement
- Low forward voltage drop, low power losses



High efficiency

- "Green" molding compound (GMC)
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

MECHANICAL DATA

Case: MicroSMP

Molding compound meets UL 94V-0 flammability rating.

"G" vs. "E" suffix defines molding as none green, "E", or green molding compound (GMC) "G".

"G" is defined as halogen-free (HF) and antimony-free molding compound that is < 50 ppm for F, Cl, Br, I and At, and < 5 ppm for Sb.

Note:

There is no industry standard for definition of HF, or GMC for

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test. "E3" terminal finish per J-STD-609

Polarity: Color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	MSS1P3	MSS1P4	UNIT	
Device marking code		13	14		
Maximum repetitive peak reverse voltage	V _{RRM}	30	40	V	
Maximum average forward rectified current (Fig. 1)	I _{F(AV)}	1.0		Α	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	25		Α	
Operating junction and storage temperature range	T _J , T _{STG}	- 55 to + 150		°C	

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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Maximum instantaneous forward voltage ⁽¹⁾	I _F = 0.5 A I _F = 1.0 A	T _J = 25 °C	V _F	0.41 0.48	- 0.55	V
	I _F = 0.5 A I _F = 1.0 A	T _J = 125 °C		0.32 0.41	- 0.46	
Maximum reverse current (1)	rated V _R	T _J = 25 °C T _J = 125 °C	I _R	8.5 4.5	200 15	μA mA
Typical junction capacitance	4.0 V, 1 MHz		CJ	50	-	pF

Note

(1) Pulse test: 300 μ s pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	MSS1P3 MSS1P4		UNIT	
Typical thermal resistance ⁽¹⁾	$egin{array}{c} {\sf R}_{ heta {\sf JA}} \ {\sf R}_{ heta {\sf JL}} \ {\sf R}_{ heta {\sf JC}} \end{array}$	125 30 40		°C/W	

Note:

(1) Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 6.0 x 6.0 mm copper pad areas $R_{\theta,JL}$ is measured at the terminal of cathode band. $R_{\theta,JC}$ is measured at the top center of the body

ORDERING INFORMATION (Example)						
PREFERRED P/N	RRED P/N UNIT WEIGHT (g) PREFERRED PACKAGE CODE BASE		BASE QUANTITY	DELIVERY MODE		
MSS1P4-E3/89A	0.006	89A	4500	7" diameter plastic tape and reel		
MSS1P4-G3/89A	0.006	89A	4500 7" diameter plastic tape a			

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

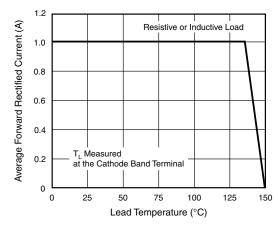


Figure 1. Maximum Forward Current Derating Curve

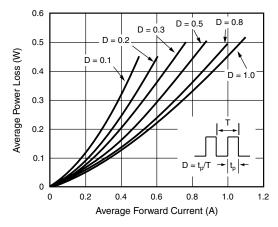


Figure 2. Forward Power Loss Characteristics



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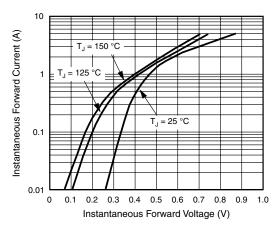


Figure 3. Typical Instantaneous Forward Characteristics

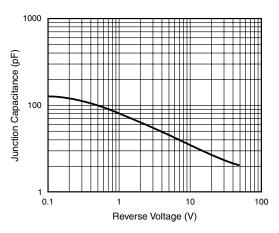


Figure 5. Typical Junction Capacitance

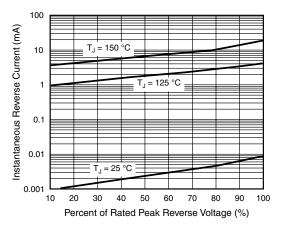


Figure 4. Typical Reverse Characteristics

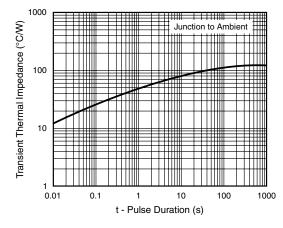


Figure 6. Typical Transient Thermal Impedance

0.020

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP 0.059 (1.50) 0.030 (0.75) Cathode Band 0.043 (1.10) 0.022 (0.55) 0.030 (0.75) 0.055 (1.40) 0.039 (0.98) 0.047 (1.20) 0.031 (0.78) 0.022 (0.55) 0.091 (2.30) 0.083 (2.10) 0.106 (2.70) 0.091 (2.30) **Mounting Pad Layout** 0.079 0.032 (2.00)(0.80) 0.029 (0.73) 0.032 0.043 0.025 (0.63) (1.10) (0.80) 0.011 (0.27)

Document Number: 89019 Revision: 14-Apr-08 For technical questions within your region, please contact one of the following: PDD-Americas@vishay.com, PDD-Asia@vishay.com, PDD-Europe@vishay.com

0.005 (0.12)

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